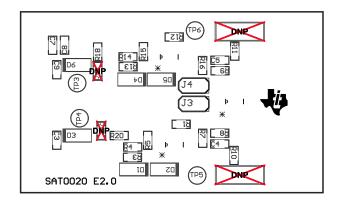
ZZ1 ■Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per Table 1

ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

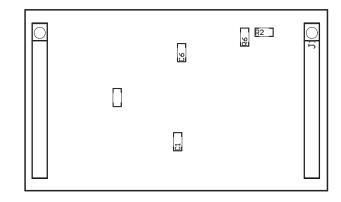
ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4 ■These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: SATOO20	REV: E2	SUN REU	: Not In VersionControl
IGNORE -> Top Overlay				
PLOT NAME = Top Assembly Drawing	GENERATED : 3/14/2	2014 5: 20: 45	PM	TEXAS INSTRUMENTS



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: SATOO20	REV: E2	SUN REU	: Not In VersionControl
	Bottom Overlay <- January			
PLOT NAME = Bottom Assembly Drawing	GENERATED : 3/14/2	2014 5: 20: 48	PM	TEXAS INSTRUMENTS

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